



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



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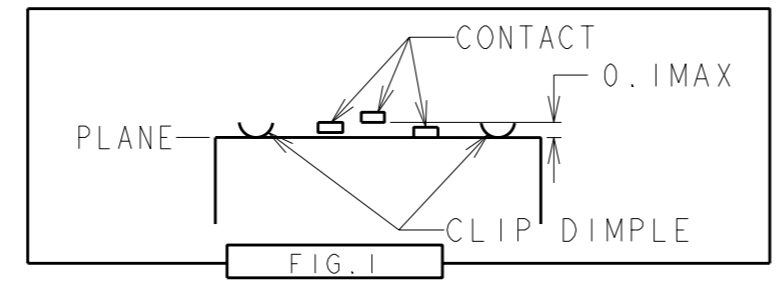
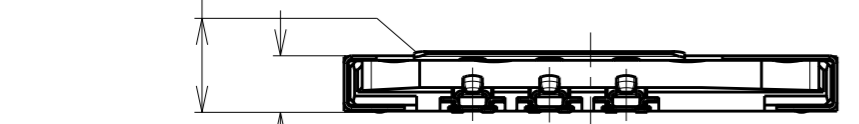
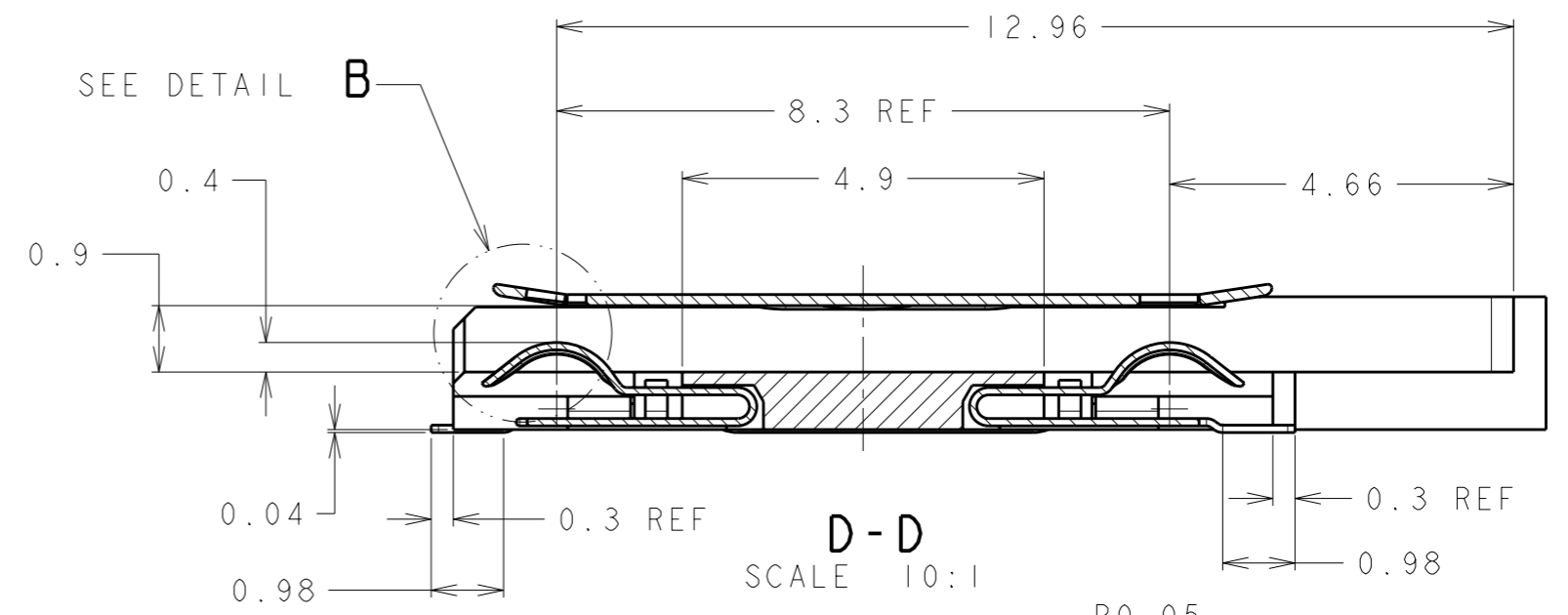
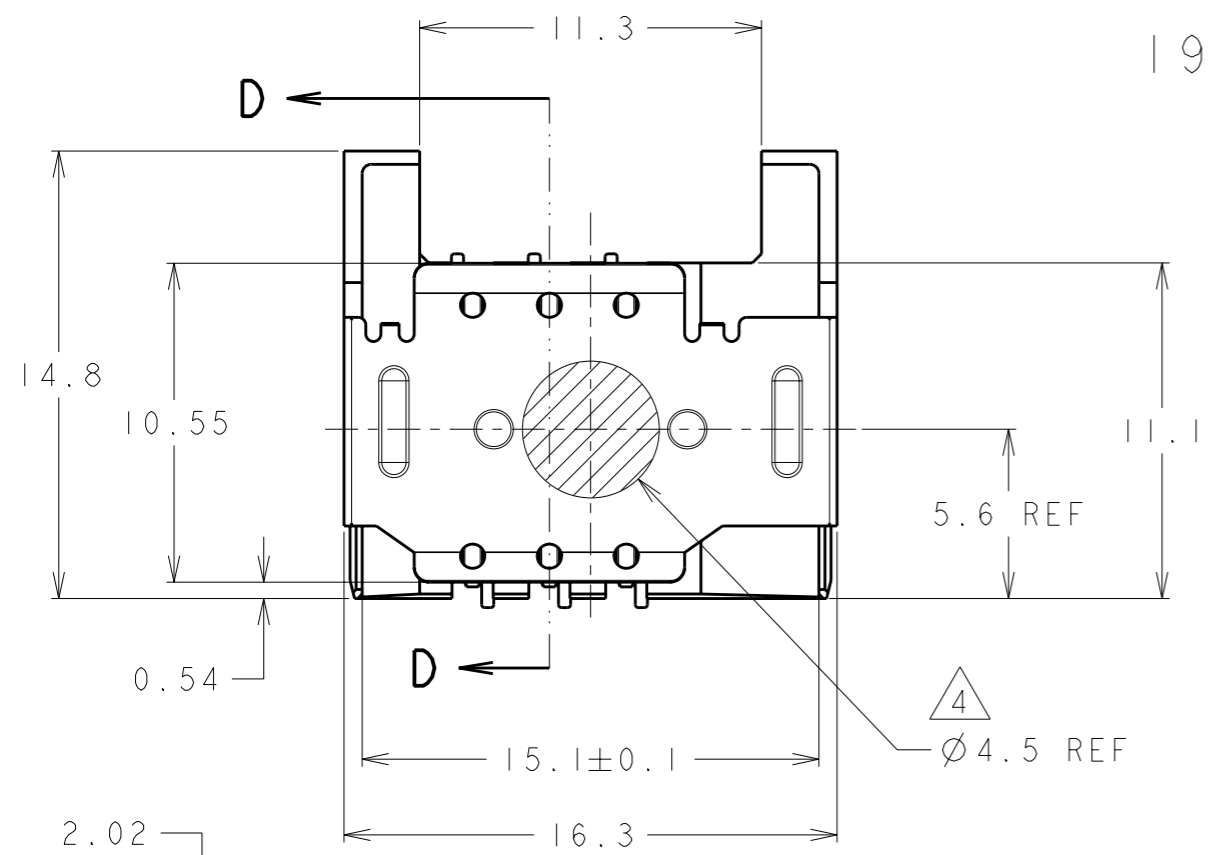
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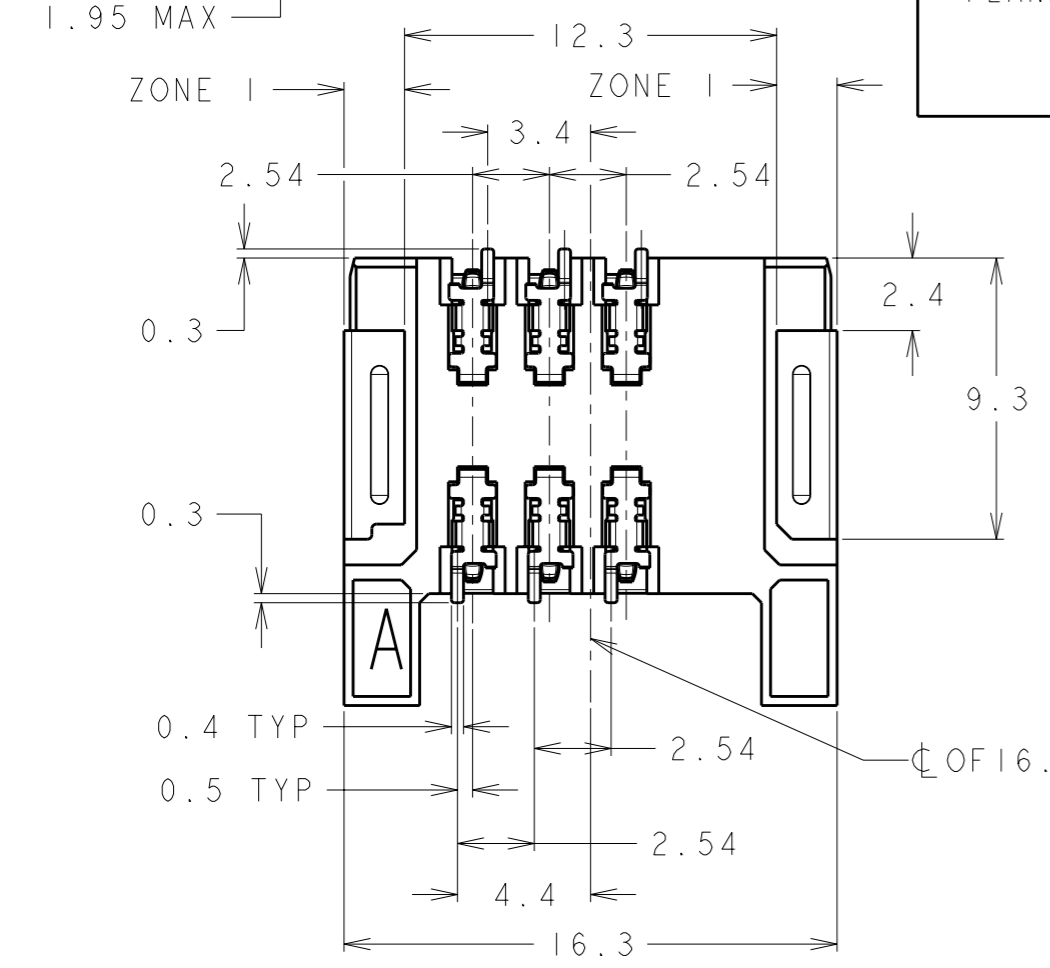
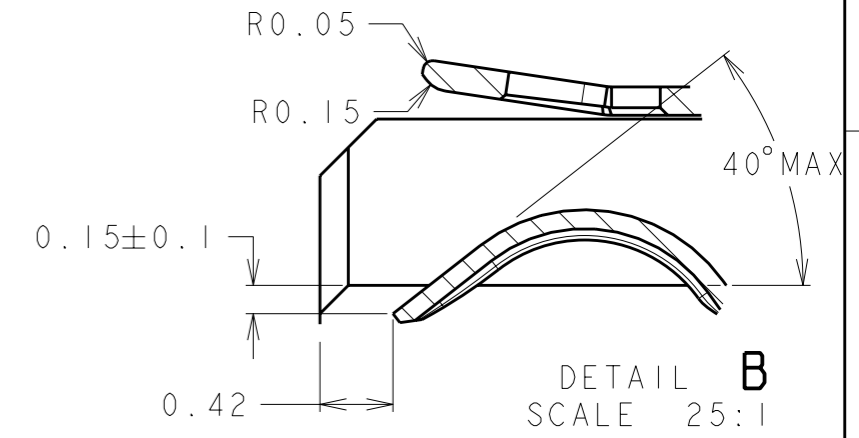
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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
ES	00	A	INITIAL RELEASE	04MAY2011	S.W S.Y
		B	REVISED	19JAN2012	S.W S.Y

1932768-1: AS SHOWN



- CONTACT: COPPER ALLOY
 ALL OVER Ni: 1.27um MIN.
 CONTACT AREA PdNi: 1.0um MIN. Au: 0.2um MIN.
 SOLDERING AREA Au: 0.05um MIN.
 - CLIP: SUS
 ALL OVER Ni: 1.3um MIN.
 Tin: 1um MIN(ZONE I).
 - HOUSING: THERMOPLASTIC
- RECOMMENDED SOLDERING THICKNESS: 100um MIN.
 RECOMMENDED SOLDERING AREA:
 100% OF REFERENCE LAYOUT PATTERN
 - COPLANARITY: 0.1MAX. (SEE FIG.1)
 - REFERENCE PICK & PLACE AREA.

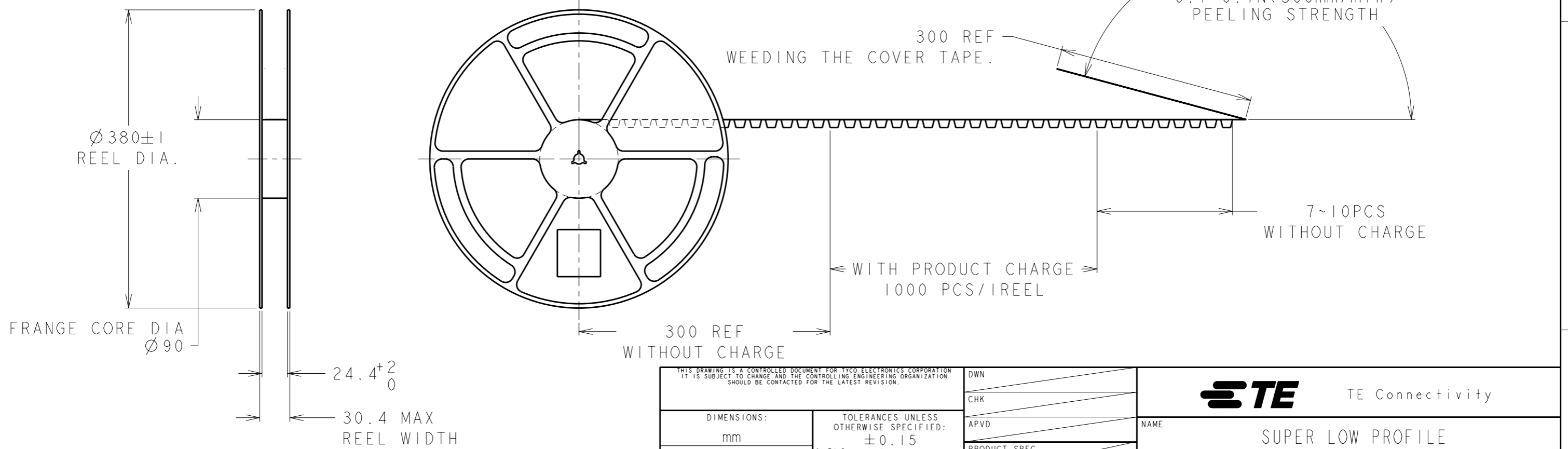
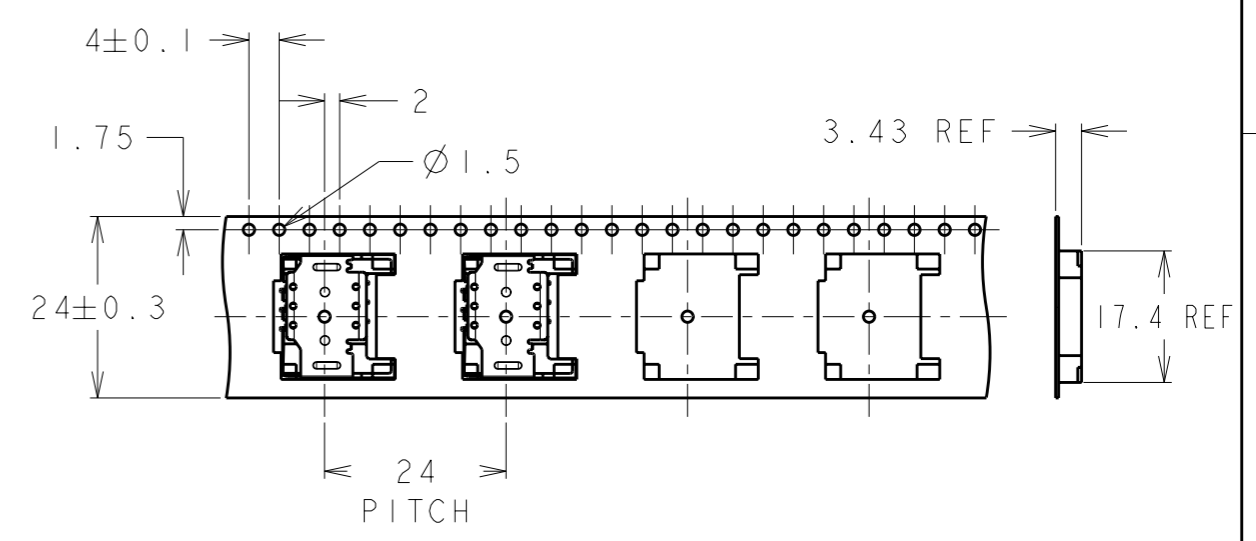
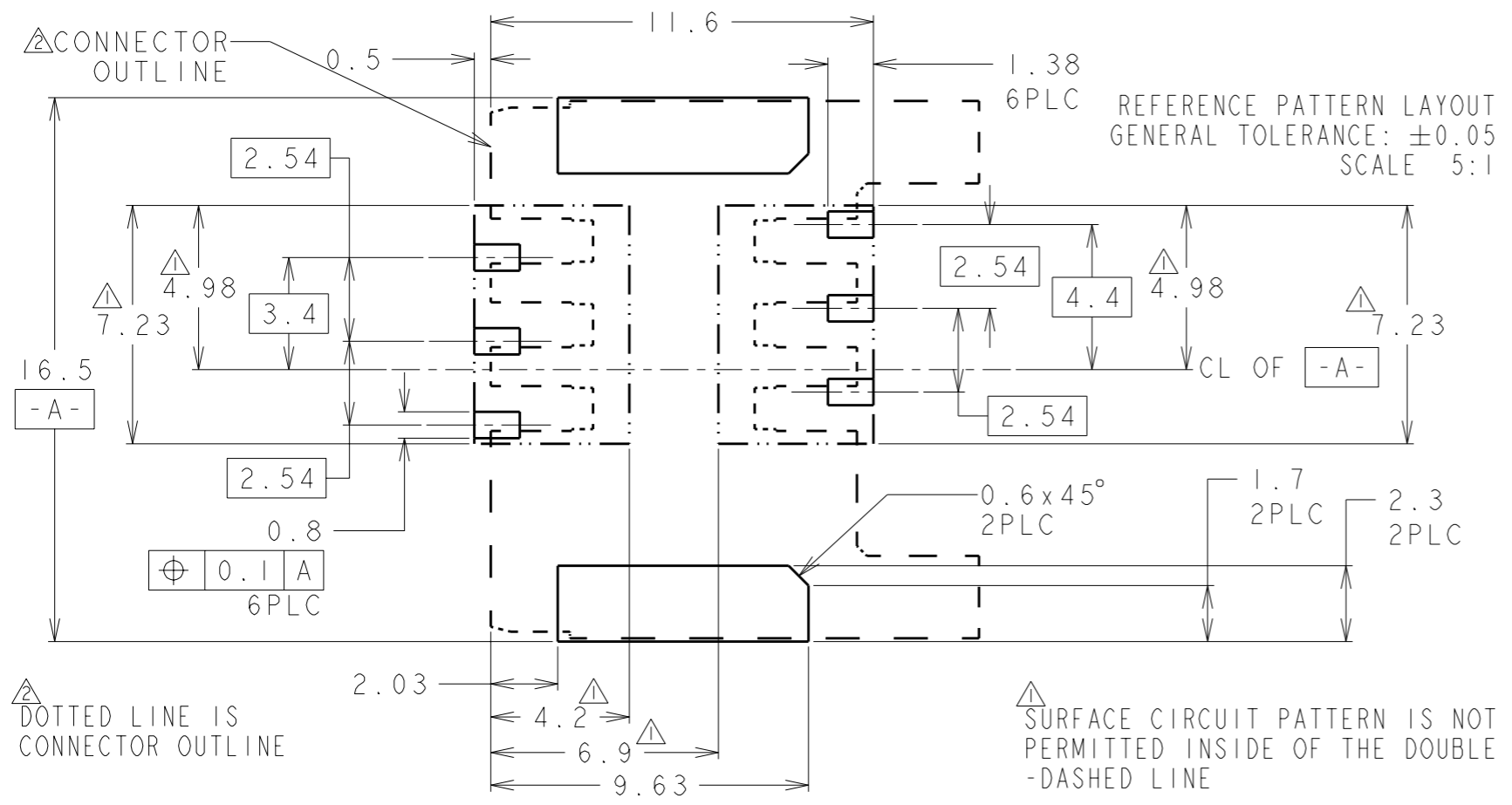


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DIMENSIONS: mm		CHK	Sabrina Wang	
TOLERANCES UNLESS OTHERWISE SPECIFIED: ±0.15		APVD	Wenke He	
0 PLC ± 1 PLC ± 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ±5°		PRODUCT SPEC	3DEC2010	NAME
MATERIAL		APPLICATION SPEC	108-115024	SUPER LOW PROFILE SIM H=1.95 WITH FLANGE
FINISH		WEIGHT	0.46g	SIZE
CUSTOMER DRAWING		A300779		CAGE CODE
SCALE 4:1		C=1932768		DRAWING NO
SHEET 1 OF 2		REV B		RESTRICTED TO

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LOC	DIST	REVISIONS				
P	LTR	DESCRIPTION	DATE	DWN	APVD	
ES	00	-	SEE SHEET 1	-	-	



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DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:
mm	± 0.15
	0 PLC \pm
	1 PLC \pm
	2 PLC \pm
	3 PLC \pm
	4 PLC \pm
	ANGLES $\pm 5^\circ$
MATERIAL	FINISH

DWN	TE Connectivity NAME SUPER LOW PROFILE SIM H=1.95 WITH FLANGE
CHK	
APVD	
PRODUCT SPEC	
APPLICATION SPEC	
WEIGHT	SIZE A300779
CUSTOMER DRAWING	CAGE CODE C-1932768
	DRAWING NO SCALE 4:1
	RESTRICTED TO SHEET 2 OF 2
	REV B